



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SO-8 SOLDER PROCESS					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	140	70 000	200 °C + N2	0	0
HAST	967	91 750	130 °C, 85 % RH	0	0
Pressure Pot	1558	149 568	121°, 15 PSIG	0	0
Solder DUNK	405	1215	260 °C, 10 s	0	0
Temp. Cycle	3053	1 394 000	-55 °C to 150 °C	0	0